

User guide for REF-DR3KIMBGSIC2MA

Reference design for servo motor and drive integration

UG 2024-16

About this document

Scope and purpose

This user guide provides an overview of REF-DR3KIMBGSIC2MA including its main features, key data, pin assignments, and mechanical dimensions. REF-DR3KIMBGSIC2MA is a reference design that contains two PCBs (driver board and power board), a driver circuit, and a 3-phase inverter for motor-drive applications. The driver circuit is based on the EiceDRIVER[™] compact single-channel isolated gate driver 1ED3122MC12H with Miller clamp function. The 2nd generation CoolSiC[™] MOSFET, IMBG120R040M2H, is the main component in the 3-phase inverter. REF-DR3KIMBGSIC2MA has been developed to provide initial support to customers in designing servo motors with integrated inverters using EiceDRIVER[™] IC and CoolSIC[™] MOSFET. This reference design is the power component of an integrated servo motor solution, which is an Infineon joint development project with partner JingChuan and Maxsine.



Note: Please note that this product is not qualified according to the AEC Q100 or AEC Q101 documents of the Automotive Electronics Council

Intended audience

This user guide is intended for all technical specialists working with REF-DR3KIMBGSIC2MA.





Reference board/kit

Infineon product(s) embedded on this PCB have functions and form factor close to a commercial design. PCB and auxiliary circuits are optimized for the final design.

Note: Boards do not necessarily meet safety, EMI, and quality standards (for example UL, CE) requirements.

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Please note the following warnings regarding the hazards associated with development systems.



Table 1Safety precautions

<u>A</u>	Warning: The DC link potential of this board is up to 1000 VDC. When measuring voltage waveforms by oscilloscope, high voltage differential probes must be used. Failure to do so may result in personal injury or deat h.
4	Warning : The evaluation or reference board contains DC bus capacitors which take time to discharge after removal of the main supply. Before working on the drive system, wait five minutes for capacitors to discharge to safe voltage levels. Failure to do so may result in personal injury or death. Darkened display LEDs are not an indication that capacitors have discharged to safe voltage levels.
4	Warning: The evaluation or reference board is connected to the grid input during testing. Hence, high-voltage differential probes must be used when measuring voltage waveforms by oscilloscope. Failure to do so may result in personal injury or death. Darkened display LEDs are not an indication that capacitors have discharged to safe voltage levels.
4	Warning: Remove or disconnect power from the drive before you disconnect or reconnect wires, or perform maintenance work. Wait five minutes after removing power to discharge the bus capacitors. Do not attempt to service the drive until the bus capacitors have discharged to zero. Failure to do so may result in personal injury or death.
555	Caution: The heat sink and device surfaces of the evaluation or reference board may become hot during testing. Hence, necessary precautions are required while handling the board. Failure to comply may cause injury.
	Caution: Only personnel familiar with the drive, power electronics and associated machinery should plan, install, commission and subsequently service the system. Failure to comply may result in personal injury and/or equipment damage.
	Caution: The evaluation or reference board contains parts and assemblies sensitive to electrostatic discharge (ESD). Electrostatic control precautions are required when installing, testing, servicing or repairing the assembly. Component damage may result if ESD control procedures are not followed. If you are not familiar with electrostatic control procedures, refer to the applicable ESD protection handbooks and guidelines.
	Caution: A drive that is incorrectly applied or installed can lead to component damage or reduction in product lifetime. Wiring or application errors such as undersizing the motor, supplying an incorrect or inadequate AC supply, or excessive ambient temperatures may result in system malfunction.
	Caution: The evaluation or reference board is shipped with packing materials that need to be removed prior to installation. Failure to remove all packing materials that are unnecessary for system installation may result in overheating or abnormal operating conditions.

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1 The board at a glance

The board at a glance 1

REF-DR3KIMBGSIC2MA is the inverter and gate driver board to demonstrate an integrated servo motor and drive. The driver circuit is based on the EiceDRIVER[™] compact single-channel isolated gate driver, 1ED3122MC12H, with Miller clamp function [1]. Second generation CoolSiC[™] MOSFET, IMBG120R040M2H, is the main component for the 3-phase inverter [2].



Figure 1 Integrated servo motor with drive

The full set consists of: an inverter board, a gate driver board, a controller board, and a servo motor, as shown in Figure 1. The control board and the motor are not part of the reference design. To evaluate the electrical performance of the system, iMOTION™ MADK EVAL-M1-101TF can be used to provide a simple control. A heatsink and a fan are included for easy evaluation, even though the system can work without a cooling fan. A fan cable is provided for connecting the 24 V supply on REF-DR3KIMBGSIC2MA to the fan.

1.1 **Delivery contents**

The reference design REF-DR3KIMBGSIC2MA is delivered together with complete documentation in an environment-friendly carton box.

As shown in Figure 2, the box contains:

- The reference board of size 12 cm x 12 cm x 10 cm (L x W x H) and weighing 800 grams assembled as a stack; • including an inverter board, a gate driver board, a heatsink, and a cooling fan. The PCB diameter (without heatsink) is 11cm.
- A fan cable, for connecting the 24 V supply on REF-DR3KIMBGSIC2MA to the fan •
- A user guide .
- An introduction sheet •

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1 The board at a glance





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1 The board at a glance

1.3 **Block diagram**

The inverter has a standard 3-phase, 2-level topology, with a DC link capacitor and six CoolSiC[™] MOSFETs in D²PAK (IMBG120R040M2H) package. The components are soldered on to a single layer Insulated metallic substrate (IMS) board. All the CoolSiC[™] MOSFETs are driven by an isolated gate driver EiceDRIVER[™] IC -1ED3122MC12H with Miller clamp function.



Figure 3 **Block diagram**

Main features 1.4

The main features of REF-DR3KIMBGSIC2MA are:

- 3-phase servo motor with integrated drive •
- 1200 V/40mΩ CoolSiC[™] MOSFET in SMD package (TO263-7), with .XT interconnection technology •
- Compact design: PCB diameter 110 mm, 120 mm considering the heatsink •
- Insulated metallic substrate (IMS) PCBs with high thermal conductivity •
- **Overcurrent detection** •
- Input voltage 350 800 VDC •
- Output voltage: 220 V to ~480 V •

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1 The board at a glance

Board parameters and technical data 1.5

Table 2 **Key parameters**

Parameter	Value	Condition
Input voltage (DC)	350 ~800 V	
Output voltage (AC, 3-phase)	220 ~480 V	
Output current (AC, 3-phase)	6.46 A	Input voltage = 600 V (DC)
Output max current (AC, 3-phase)	14.88 A	Input voltage = 600 V (DC)
Output power	4.2 kW	Input voltage = 600 V (DC)
Ambient temperature	0-40°C	



2 System and functional description

2.1 Commissioning

The REF-DR3KIMBGSIC2MA board is intended for evaluating a CoolSiC[™] MOSFET solution in an integrated servo drive application. The control of the servo motor is not the intended focus. This section introduces the minimum connections required to start the evaluation.

Minimum connections for the gate driver board (see Figure 4):

- An auxiliary power supply connection CN1 (input): 0 ~ 24 V DC from an external power supply
- Gate driver signal connection: J1

Minimum connections for the power board (see Figure 5):

- A DC link connection (input): 350 ~ 800 V DC from an external power supply
- A 3-phase AC (output) connection to 3-phase motor or resistor-inductor (RL) load



Figure 4 Driver board connections

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2 System and functional description



Figure 5 Power board connections

2.2 Basic operation using a controller

Table2 indicates electrical key parameters valid for basic operation (including maximum ratings). To evaluate the electrical performance of the system, the iMOTION[™] MADK EVAL-M1-101TF control board can be used. Detailed information about the drive card can be found in [3].



Figure 6 iMotion[™] MADK EVAL-M1_101TF



2 System and functional description

The connection between REF-DR3KIMBGSIC2MA and EVAL-M1-101TF is pin-to-pin. The details are listed in Table 3 and in Table 8 (gate driver board, connector J1). An adaption cable, jumpers and extra wires are not required for the connection.

Pin number	Pin	Details	
1	PWMUH	3.3 V compatible logic output for high-side gate driver, phase U	
2	GND	Ground	
3	PWMUL	3.3 V compatible logic output for low-side gate driver, phase U	
4	GND	Ground	
5	PWMVH	3.3 V compatible logic output for high-side gate driver, phase V	
6	+3.3 V	On board 3.3 V supply	
7	PWMVL	3.3 V compatible logic output for low-side gate driver, phase V	
8	+3.3 V	Onboard 3.3 V supply	
9	PWMWH	3.3 V compatible logic output for high-side gate driver, phase W	
10	IU+	Shunt voltage, phase U	
11	PWMWL	3.3 V compatible logic output for low-side gate driver, phase W	
12	IU-	Ground	
13	GK	Gatekill signal – active low when overcurrent is detected	
14	DCBSENSE	DC bus positive voltage, scaled in 0 - 3.3 V range by a voltage divider	
15	VTH	Thermistor input	
16	IV+	Shunt voltage, phase V	
17	IV-	Ground	
18	IW+	Shunt voltage, phase W	
19	IW-	Ground	
20	VCC	Defined for 15 V power supply (not used on this board)	

Table 3 CoolSiC [™] MADK-M1 20-pin interface connector for the control







3 System design

3 System design

3.1 Schematics

The schematics of the power board is shown in Figure 8.







The schematics of the gate driver board is shown in **Error! Reference source not found.** and Figure 10.





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3 System design



Figure 10 The schematics of the gate driver board (REF-DR3KIMBGSIC2MA)



3.2 Layout

The power board is a single-layer IMS board. The gate driver board is a 4-layer PCB board. The layouts of the boards are shown in Figure 11 and Figure 12 respectively.



Figure 11 The layout of the power board (REF-DR3KIMBGSIC2MA)



3 System design



Figure 12 The layout of the driver board (REF-DR3KIMBGSIC2MA)

3.3 Bill of material

The complete bill of material is available in the Download section of Infineon's website.

No.	Designator	Value	Description	Manufacturer	Manufacturer P/N
10	Q1, Q2, Q3, Q4, Q5, Q6	IMBG120R040 M2H	CoolSiC 1200V SiC Trench MOSFET Silicon Carbide MOSFET, Sense pin for optimized switching performance, Reduction of system complexity and cost, Qualified for industrial applications	Infineon Technologies	IMBG120R040M2H
21	X1, X2, X4, X5	copper pillar, connect Power Board to Driver Board	copper pillar from WURTH, manufacture order number 971190324	Wurth	971190324

Table 4BOM of the power board

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No.	Designator	Value	Description	Manufacturer	Manufacturer P/N
2	C3, C4, C8, C9, C14, C15	100pF	CAP / CERA / 100pF / 25V / 10% / X7R (EIA) / -55°C to 125°C / 0603(1608) / SMD / -	Wurth Elektronik	885012206053
12	C48	100pF	CAP / CERA / 100pF / 50V / 5% / C0G (EIA) / NP0 / -55°C to 125°C / 0805(2012) / SMD / -	Wurth Elektronik	885012007057
19	J1	6.1302E+11	WR-PHD 2.54 mm Angled Dual Socket Header	Wurth Elektronik	613020243121
20	L1	10uH	IND / STD / 10uH / 3.05A / 20% / - 40°C to 125°C / 100.8mR / SMD / Inductor, SMD, 2.37 mm pitch, 2 Pin, 4.10 mm L X 4.10 mm W X 3.10 mm H body / SMD / -	Wurth Elektronik	74438357100
21	P1, P3, P10	61300621121	WR-PHD Dual Pin Header, 2.54mm Pitch, Double row, 6 Pins	Wurth Elektronik	61300621121
22	P2, P4, P5, P6	61300421121	Header, 4pins, 2.54mm pitch, Board to Board	Wurth Elektronik	61300421121
37	U1, U2, U3, U4, U5, U6	1ED3122MC12H	Single channel isolated IGBT gate driver IC	Infineon Technologies	1ED3122MC12H

Table 5 BOM of the gate driver board

3.4 Connector details

General information about the connectors of the REF-DR3KIMBGSIC2MA evaluation board is provided in the following tables.

Table 6Power board board connectors

PIN	Label	Function
P+,P-	P+,P-	Power supply input for DC link
U,V,W	U,V,W	AC power output for motor
VDD	P24V	Auxiliary power supply input
R24	R24	Source current test point

PIN	Label	Function	
TP2	GH	High-side gate test point	
TP4	GL	Low-side gate test point	
TP3	SH	High-side source test point	
TP5	SL	Low-side source test point	
TP1	GND	Ground test point	



3 System design

Table 8 Gate driver connector J1

Pin number	Pin	Details	
1	PWMUH	Gating signal, high side, phase U	
2	GND	Ground	
3	PWMUL	Gating signal, low side, phase U	
4	GND	Ground	
5	PWMVH	Gating signal, high side, phase V	
6	+3.3V	On board 3.3 V supply	
7	PWMVL	Gating signal, low side, phase V	
8	+3.3V	On board 3.3 V supply	
9	PWMWH	Gating signal, high side, phase W	
10	IU+	Shunt voltage phase U	
11	PWMWL	Gating signal, low side, phase W	
12	IU-	Ground	
13	GK	Gatekill signal – active low when overcurrent is detected	
14	DCBSENSE	DC bus positive voltage, scaled in 0 - 3.3 V range by a voltage divider	
15	VTH	Thermistor input	
16	IV+	Shunt voltage phase V	
17	IV-	Ground	
18	IW+	Shunt voltage phase W	
19	IW-	Ground	
20	VCC	Defined for 15 V power supply (not used in this board)	



4 System performance

System performance 4

Efficiency of the 2nd generation CoolSIC[™] MOSFET was proven through a system performance test.

The test platform comprised:

- A DC power supply •
- A DC high-voltage power supply •
- A precision power analyzer •
- A thermal camera •
- An RL load •
- An oscilloscope •
- MADK EVAL-M1_101TF •
- **REF-DR3KIMBGSIC2MA** .

The setup and block diagram of the experiment are shown in Figure 13 and Figure 14, respectively.



Figure 13 Image of the test setup

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4 System performance



Figure 14 Block diagram of the test setup

The test was performed under the following conditions:

- 600 V DC bus voltage
- 24 V supplied for auxiliary power supply
- Board fan in operation versus board fan not in operation
- 8 kHz switching frequency
- 3 x 33 Ω load resistance

Figure 15 shows the V_{gs} (channel 1) and V_{ds} (channel 4) measured on the low side of the device, and the phase current I_{ph} (channel 3) measured on the U inverter leg.

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4 System performance



Figure 15 50 Hz phase current

More information was obtained using a precision power analyzer. The results are listed in Table 9.

Table 9 **Power analyzer results**

	One phase (RMS)	DC link
Voltage	218.12 V	601.6 V
Current	6.46 A	7.12 A
Active power	1.408 kW	4.283 kW

The total output power with the given conditions is 4.2 kW.

Figures 16 and 17 show the images from a thermal camera when the board fan is operational and when it is disconnected, respectively. The spots Sp1 and Sp2 denote the high side and low side MOSFETs in the W inverter leg.



4 System performance



Figure 16 Thermal camera image - 600 VDC, 8 kHz switching frequency, with active fan



Figure 17 Thermal camera image - 600 VDC, 8 kHz switching frequency, without fan

With active fan high side and low side devices temperatures are respectively 27.8°C and 27.1°C. Without the fan the high side and low side devices temperatures are respectively 29.5°C and 28.4°C. In both cases the temperature does not differ more than 6°C than the ambient temperature.



References

- [1] <u>https://www.infineon.com/dgdl/Infineon-IMBG120R040M2H-DataSheet-v01_00-EN.pdf?fileId=8ac78c8c8d1b852e018d2200102020d0</u>
- [2] <u>https://www.infineon.com/dgdl/Infineon-1ED31xxMC12H- 1ED-X3_Compact-DataSheet-v01_10-EN.pdf?fileId=5546d46277fc7439017802de09e5671d</u>
- [3] [iMOTION[™] MADK EVAL-M1-101TF user manual]; <u>https://www.infineon.com/dgdl/Infineon-UG-2020-15_EVAL-M1-101TF-UserManual-v01_00-EN.pdf?fileId=5546d46277921c320177d97457631fd2</u>

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Glossary

Glossary

PCB

Printed circuit board

SMD

Surface mounted device

IMS

Insulated metallic substrate

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Revision history

Document revision	Date	Description of changes
1.00	2024-04-17	Initial version

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